

LINEAR MOSFET

Linear Mosfets are optimized for applications operating in the Linear region where concurrent high voltage and high current can occur at near DC conditions (>100 msec).

- Higher FBSOA
- Higher Power Dissipation
- RoHS Compliant
- Popular SOT-227 Package
- SOA Rated



MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	APL502J	UNIT
V_{DSS}	Drain-Source Voltage	500	Volts
I_D	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	52	Amps
I_{DM}	Pulsed Drain Current ^①	208	
V_{GS}	Gate-Source Voltage Continuous	±30	Volts
V_{GSM}	Gate-Source Voltage Transient	±40	
P_D	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	568	Watts
	Linear Derating Factor	4.55	W/°C
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C
T_L	Lead Temperature: 0.063" from Case for 10 Sec.	300	
I_{AR}	Avalanche Current ^① (Repetitive and Non-Repetitive)	52	Amps
E_{AR}	Repetitive Avalanche Energy ^①	50	mJ
E_{AS}	Single Pulse Avalanche Energy ^④	3000	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions / Part Number	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage ($V_{GS} = 0V, I_D = 250 \mu A$)	500			Volts
$I_{D(ON)}$	On State Drain Current ^② ($V_{DS} > I_{D(ON)} \times R_{DS(ON)}$ Max, $V_{GS} = 15V$)	52			Amps
$R_{DS(ON)}$	Drain-Source On-State Resistance ^② ($V_{GS} = 15V, 26A$)			0.09	Ohms
I_{DSS}	Zero Gate Voltage Drain Current ($V_{DS} = 500V, V_{GS} = 0V$)			25	μA
	Zero Gate Voltage Drain Current ($V_{DS} = 400V, V_{GS} = 0V, T_C = 125^\circ\text{C}$)			250	
I_{GSS}	Gate-Source Leakage Current ($V_{GS} = \pm 30V, V_{DS} = 0V$)			±100	nA
$V_{GS(TH)}$	Gate Threshold Voltage ($V_{DS} = V_{GS}, I_D = 2.5mA$)	2		4	Volts



CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C_{iss}	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1 \text{ MHz}$		7600	9000	pF
C_{oss}	Output Capacitance			1280	1810	
C_{rss}	Reverse Transfer Capacitance			620	930	
$t_{d(on)}$	Turn-on Delay Time	$V_{GS} = 15V$ $V_{DD} = 0.5 V_{DSS}$ $I_D = 52A @ 25^\circ C$ $R_G = 0.6\Omega$		13	26	ns
t_r	Rise Time			24	48	
$t_{d(off)}$	Turn-off Delay Time			58	87	
t_f	Fall Time			14	17	

THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			.22	$^\circ C/W$
$V_{Isolation}$	RMS Voltage (50-60 Hz Sinusoidal Waveform From Terminals to Mounting Base for 1 Min.)	2500			Volts
W_T	Package Weight		1.03		oz
			29.2		g
Torque	Maximum Torque for Device Mounting Screws and Electrical Terminations.			10	lb•in
				1.1	N•m
SOA1	Safe Operating Area $V_{DS} = 400 V$, $I_{DS} = 0.75A$, $t = 20 \text{ sec.}$, $T_C = 60^\circ C$	300			Watts

- ① Repetitive Rating: Pulse width limited by maximum junction temperature. ③ See MIL-STD-750 Method 3471
 ② Pulse Test: Pulse width < 380 μS , Duty Cycle < 2% ④ Starting $T_J = +25^\circ C$, $L = 2.22mH$, $R_G = 25\Omega$, Peak $I_L = 52A$
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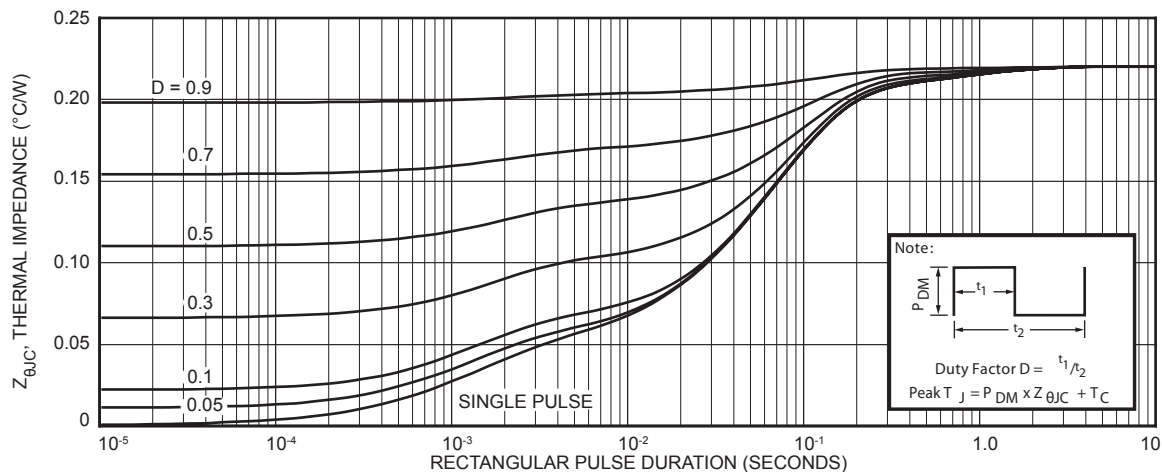


FIGURE 1, MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs PULSE DURATION

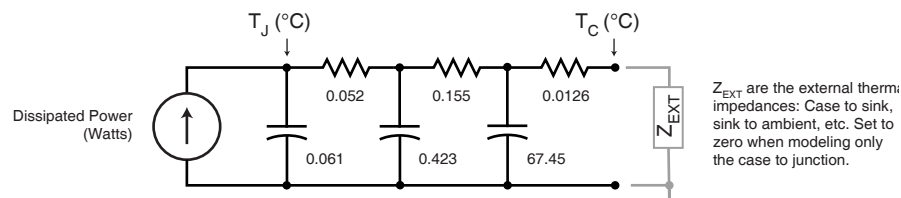


FIGURE 1a, TRANSIENT THERMAL IMPEDANCE MODEL

Typical Performance Curves

APL502J

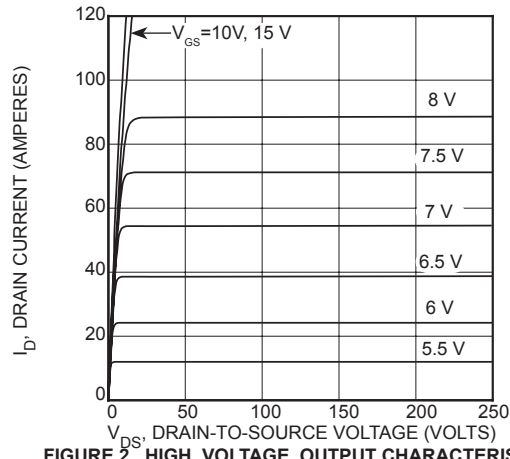


FIGURE 2, HIGH VOLTAGE OUTPUT CHARACTERISTICS

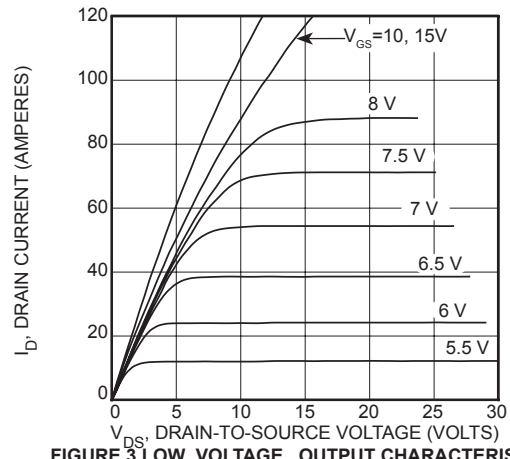


FIGURE 3, LOW VOLTAGE OUTPUT CHARACTERISTICS

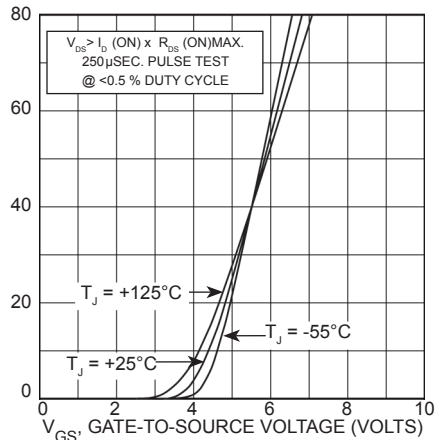


FIGURE 4, TRANSFER CHARACTERISTICS

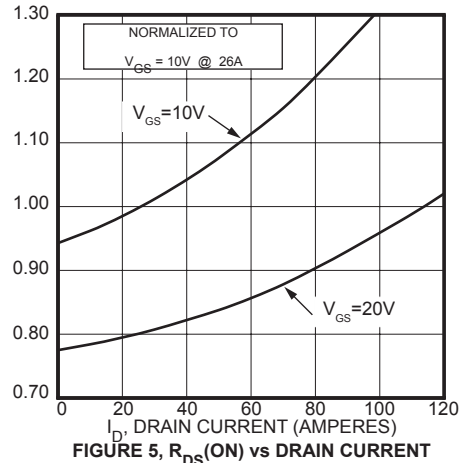


FIGURE 5, $R_{DS(ON)}$ vs DRAIN CURRENT

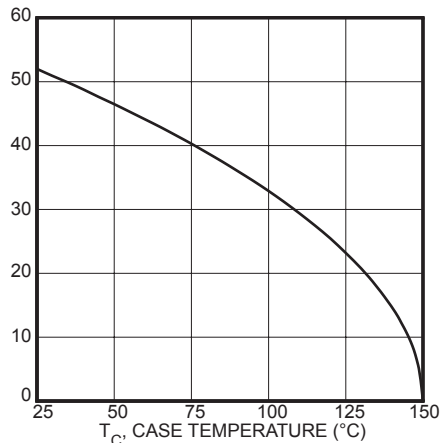


FIGURE 6, MAXIMUM DRAIN CURRENT vs CASE TEMPERATURE

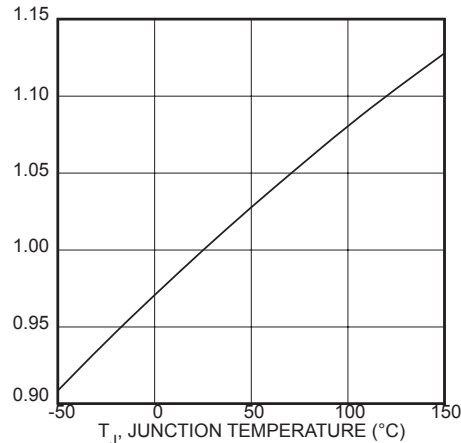


FIGURE 7, BREAKDOWN VOLTAGE vs TEMPERATURE

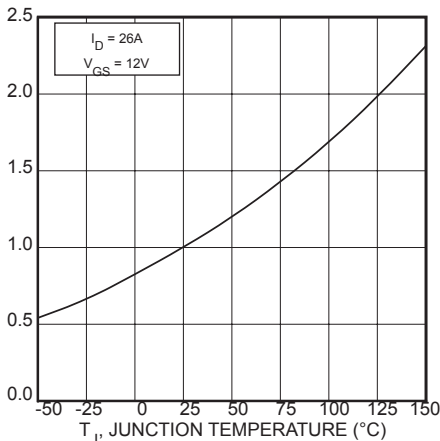


FIGURE 8, ON-RESISTANCE vs. TEMPERATURE

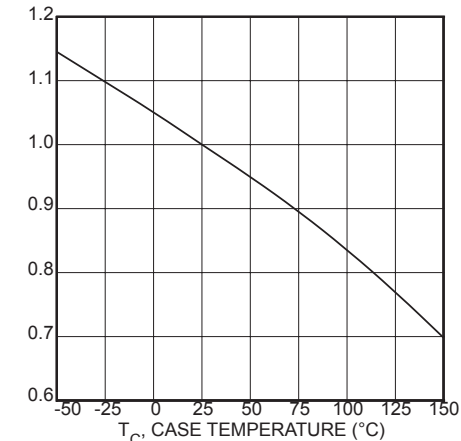


FIGURE 9, THRESHOLD VOLTAGE vs TEMPERATURE

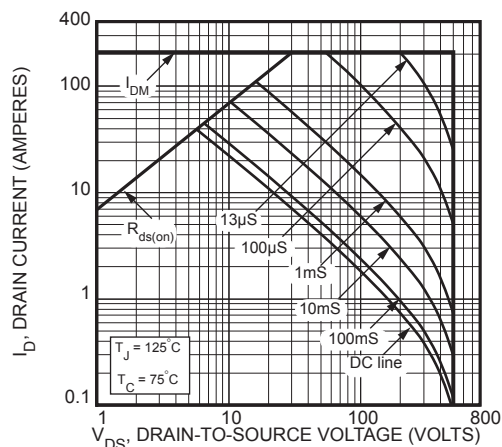


FIGURE 10, FORWARD SAFE OPERATING AREA

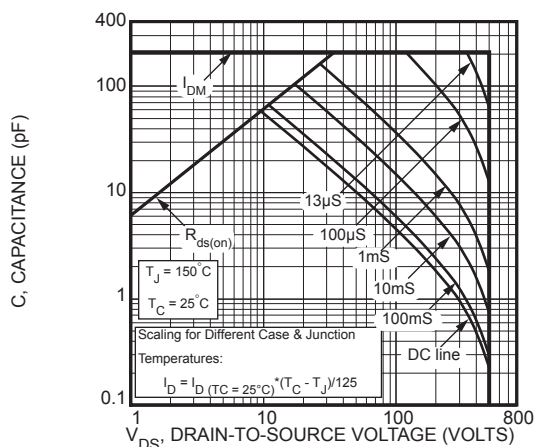


FIGURE 11, MAXIMUM FORWARD SAFE OPERATING AREA

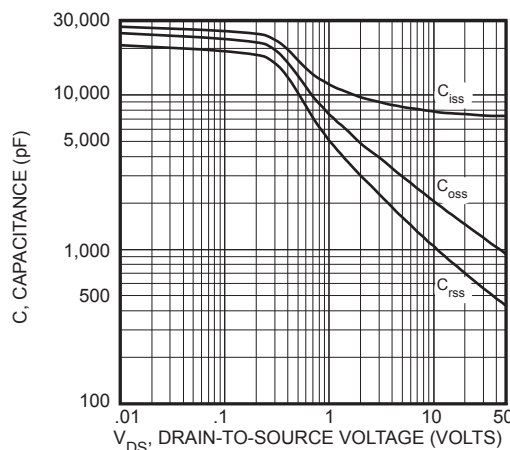
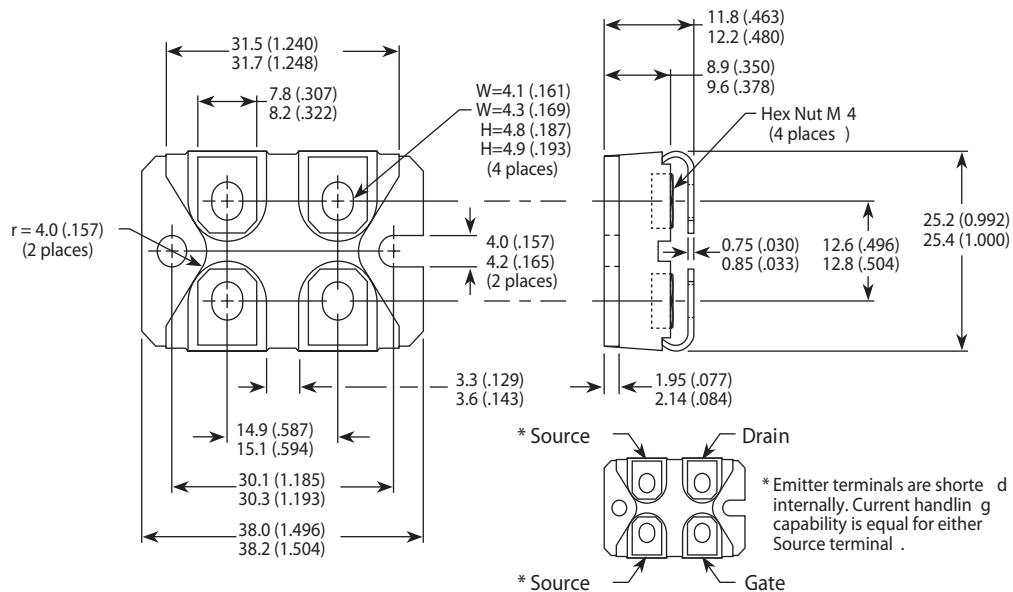


FIGURE 12, CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE

SOT-227 (ISOTOP®) Package Outline



Dimensions in Millimeters

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